

**Amendments to the Claims are as follows:**

1. (Currently Amended) A circuit module comprising:
  - a circuit substrate having a first wiring pattern provided on a first surface on one side thereof and a second wiring pattern provided on a second surface on another side thereof;
  - a first flip chip component mounted on the first surface; and
  - a second flip chip component mounted on the second surface,wherein an insulation layer is formed on the first or second surface such that the insulation layer substantially entirely covers the first or second surface and wherein the first or second flip chip component is embedded in the insulation layer.
2. (Original) A circuit module according to Claim 1, wherein an exposed surface of the insulation layer is a flat surface that is in parallel with the first or second surface.
3. (Currently Amended) A circuit module according to Claim 1, wherein an electrical component is mounted on the first surface in addition to the first flip chip component and wherein the second flip chip component mounted on the second surface is embedded in the insulation layer.
4. (Currently Amended) A circuit module according to Claim 3, wherein a terminal portion is formed on the second surface in a state in which the terminal portion is connected to the second wiring pattern and wherein the terminal portion is embedded in the insulation layer with an end face thereof exposed.

5. (Original) A circuit module according to Claim 4, wherein the terminal portion can be connected to a conductive pattern on a mother substrate with a surface of the insulation layer placed on the mother substrate.

6. (Currently Amended) A method of manufacturing a circuit module, comprising the steps of:

providing a circuit substrate having a first wiring pattern provided on a first surface on one side thereof and a second wiring pattern provided on a second surface on another side thereof, a first flip chip component mounted on the first surface, and a second flip chip component mounted on the second surface;

forming an insulation layer such that the insulation layer substantially entirely covers the second surface after the second flip chip component is mounted on the second surface, the second flip chip component being embedded therein; and

mounting the first flip chip component on the first surface using the insulation layer as a datum.

7. (Original) A method of manufacturing a circuit module according to Claim 6, wherein the insulation layer is formed by injection- molding or applying a material.

8. (Original) A method of manufacturing a circuit module according to Claim 6, wherein an exposed surface of the insulation layer is polished or cut to make the exposed surface of the insulation layer into a flat surface that is in parallel with the second surface.

9. (Original) A method of manufacturing a circuit module according to Claim 6, wherein a terminal portion is formed on the second surface and wherein the terminal portion is embedded in the insulation layer with an end face of the terminal portion exposed.